

SOT998-1

plastic low profile fine-pitch ball grid array package; 459 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA459
Package type industry code	LFBGA459
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-3-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		1.15	-	1.26	1.4	mm
A ₂	package height		0.95	-	1.01	1.1	mm
n ₂	actual quantity of termination		-	-	459	-	



2. Package outline

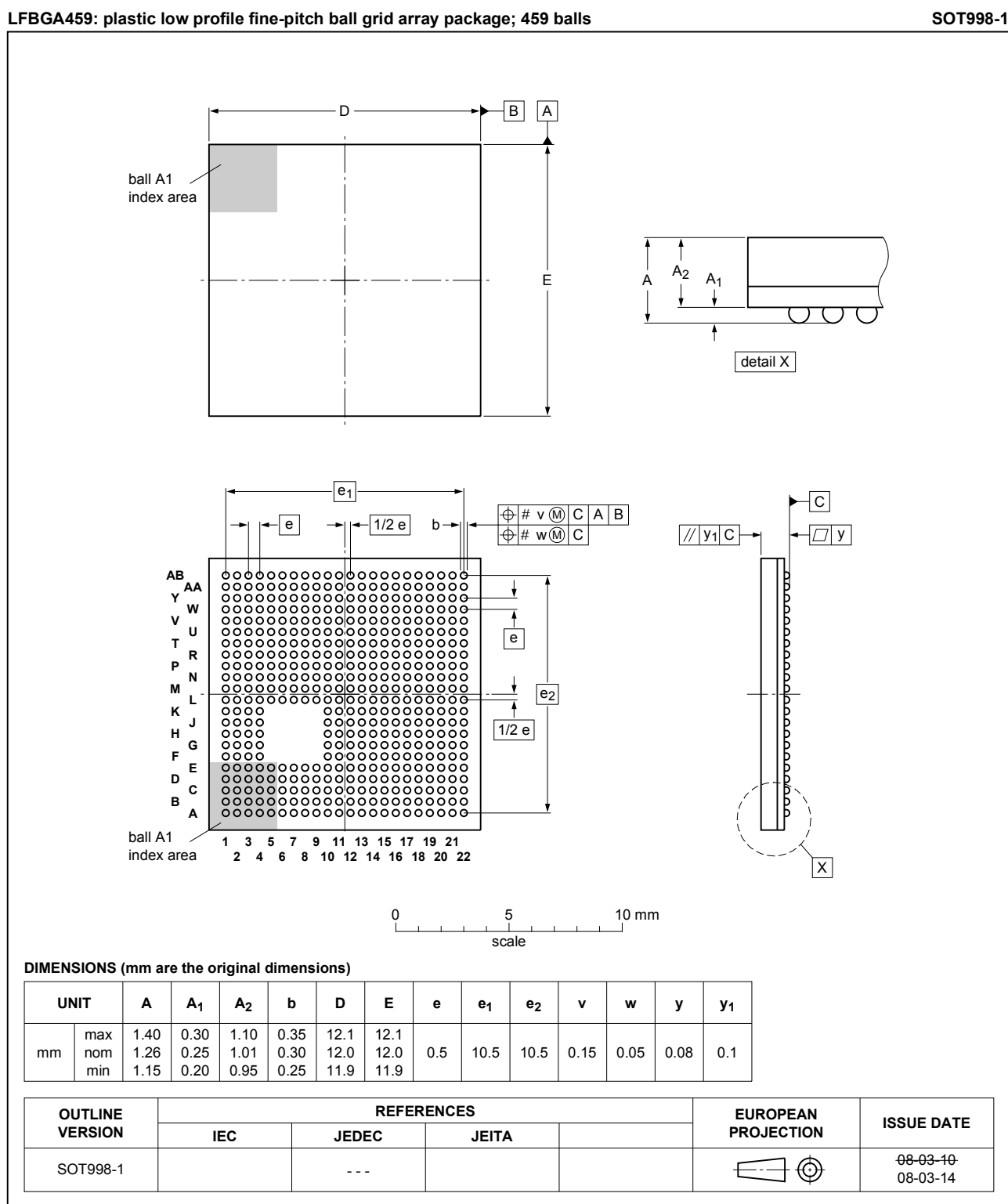


Fig. 1. Package outline LFBGA459 (SOT998-1)

3. Soldering

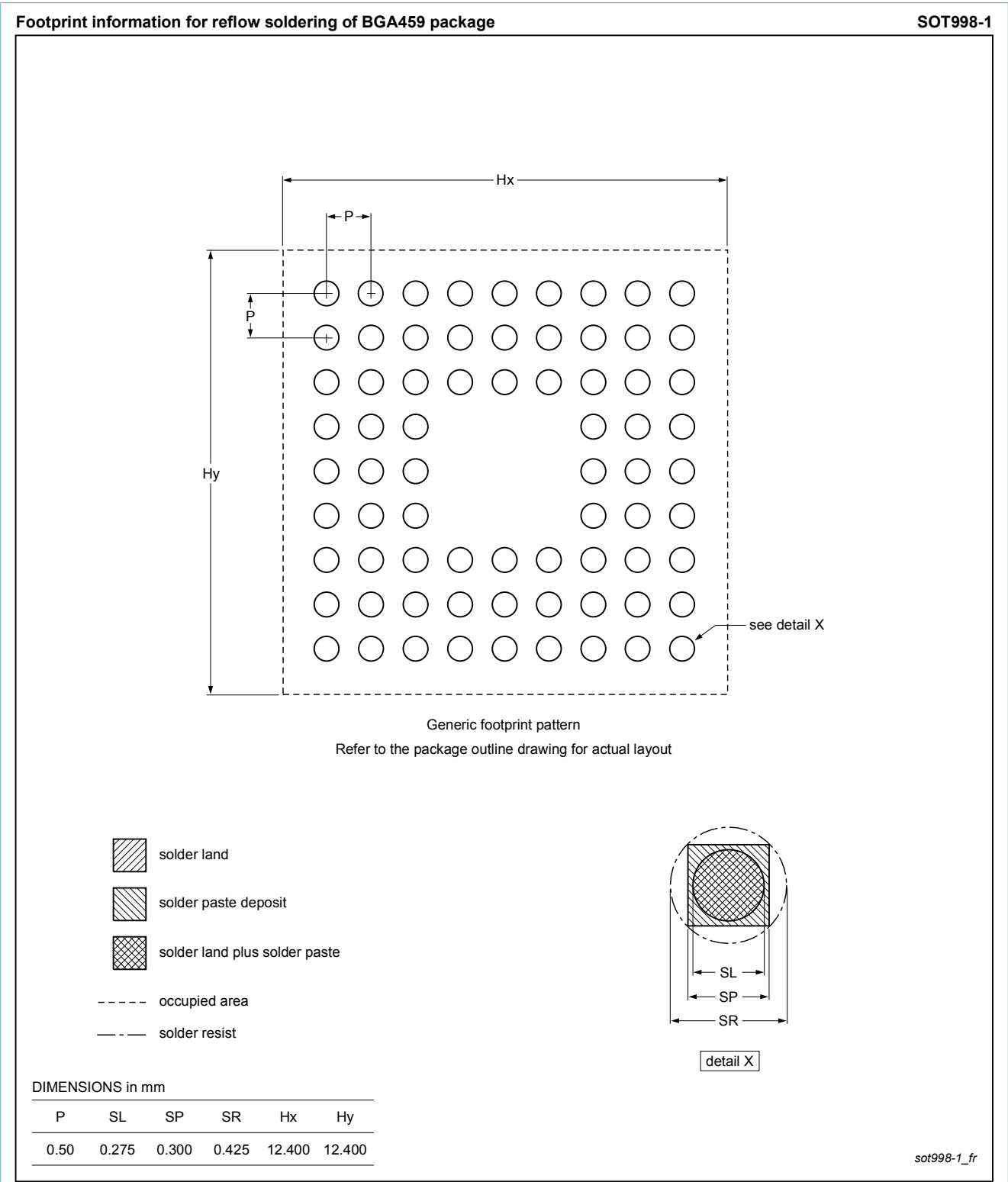


Fig. 2. Reflow soldering footprint for LFBGA459 (SOT998-1)

4. Legal information

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